AMENDMENTS TO THE CLAIMS

Claim 1 (Original) A substrate holder for holding a circuit board, comprising:

a main body; and

a holding surface formed on the main body for allowing a circuit board to adhere to the holding surface,

wherein the holding surface includes:

a first adhesive holding region for holding the circuit board with a first tackiness; and

a second adhesive holding region for holding the circuit board with a second tackiness which is different from the first tackiness, such that the first and second adhesive holding regions hold the circuit board in cooperation.

Claim 2 (Original) The substrate holder according to claim 1, further comprising an adhesive material provided on the main body,

wherein the first adhesive holding region and the second adhesive holding region are on a surface of the adhesive material.

Claim 3 (Original) The substrate holder according to claim 2, wherein the first adhesive holding region and the second adhesive holding region are within one area of the adhesive material provided on the main body.

Claim 4 (Currently Amended) The substrate holder according to claim 2~~ or 3~~, wherein,

the first adhesive holding region and the second adhesive holding region are composed of the same adhesive material, and

the first adhesive holding region and the second adhesive holding region are imparted with different surface undulation characteristics.

Claim 5 (Original) The substrate holder according to claim 4, wherein the first adhesive holding region and the second adhesive holding region have different surface coarsenesses.

Claim 6 (Currently Amended) The substrate holder according to claim 1 ~~any of claims 1 to 5~~, wherein

the first adhesive holding region and the second adhesive holding region are provided within one plane.

Claim 7 (Currently Amended) The substrate holder according to claim 1 ~~any of claims 1 to 5~~, wherein

the first adhesive holding region and the second adhesive holding region are differentiated in level.

Claim 8 (Original) The substrate holder according to claim 7, wherein one of the first and second adhesive holding regions surrounds the other adhesive holding region, and the other adhesive holding region projects from the one adhesive holding region.

Claim 9 (Original) The substrate holder according to claim 7, wherein a bottom of a depression surrounded by one of the first and second adhesive holding regions comprises the other adhesive holding region.

Claim 10 (Currently Amended) The substrate holder according to claim 1 ~~any of claims 1 to 7~~, wherein,

the first tackiness is less than the second tackiness, and

the second adhesive holding region is confined within the first adhesive holding region.

Claim 11 (Currently Amended) The substrate holder according to claim 1 ~~any of claims 1 to 10~~, wherein

the first tackiness is less than the second tackiness, and

a through hole for receiving a pin is provided in the first adhesive holding region, the pin being used when peeling off the circuit board.

Claim 12 (Original) The substrate holder according to claim 11, wherein an air outlet is provided in the second adhesive holding region.

Claim 13 (Currently Amended) The substrate holder according to claim 1 ~~any of claims 1 to 7~~, wherein

the first tackiness is less than the second tackiness, and

the first adhesive holding region is confined within the second adhesive holding region.

Claim 14 (Currently Amended) The substrate holder according to claim 1 ~~any of claims 1 to 13~~, wherein

the holding surface includes a plurality of sets of the first adhesive holding region and the second adhesive holding region.

Claim 15 (Original) A substrate holder for holding a flexible circuit board, comprising:

a main body; and

an adhesive material formed on the main body for allowing a circuit board to adhere to the adhesive material,

wherein an undulating pattern for tackiness adjustment is provided on a surface of the adhesive material.

Claim 16 (Currently Amended) The substrate holder according to claim ~~2 or~~ 15, wherein

the adhesive material is silicone rubber, polyurethane rubber, or fluorine rubber.

Claim 17 (Currently Amended) The substrate holder according to claim 1 ~~any of claims 1 to 16~~ being used as a pallet for carrying the circuit board.

Claim 18 (Original) A method for producing a substrate holder for holding a circuit board, comprising the steps of:

placing an adhesive material on a main body to become the substrate holder; and

pressing a mold against the adhesive material while heating the mold, the mold having an undulating pattern for tackiness adjustment provided thereon.

Claim 19 (Original) The method according to claim 18, wherein

the mold includes a region in which a first undulating pattern is formed and a region in which a second undulating pattern is formed.

Claim 20 (Original) The method according to claim 19, wherein,

the mold is differentiated in level between the region in which the first undulating pattern is formed and the region in which the second undulating pattern is formed.

Claim 21 (Original) A method for producing a mold to be used for forming an undulating pattern for tackiness adjustment on an adhesive material of a substrate holder for holding a circuit board, comprising the steps of:

forming a pressing surface of the mold; and

blasting minute particles against the pressing surface.

Claim 22 (Original) The method according to claim 21, further comprising, before the step of blasting minute particles:

a step of placing a mask so as to oppose the pressing surface.

Claim 23 (Currently Amended) The method according to claim 21 ~~or 22~~, further comprising, after the step of blasting minute particles:

a step of placing a mask so as to oppose the pressing surface; and

blasting another type of minute particles against the pressing surface through the mask.

Claim 24 (Original) A method for producing a mold to be used for forming an undulating pattern for tackiness adjustment on an adhesive material of a substrate holder for holding a circuit board, comprising the steps of:

forming a pressing surface of the mold; and

forming an undulating pattern on the pressing surface by chemical etching.

Claim 25 (New) The substrate holder according to claim 15 being used as a pallet for carrying the circuit board.

Claim 26 (New) The substrate holder according to claim 2, wherein

the adhesive material is silicone rubber, polyurethane rubber, or fluorine rubber.